



TE Internal #: 8-2355632-1
Double Data Rate (DDR) 5, Board-to-Component, 288 Position,
Surface Mount, Vertical Module Orientation, .85 mm [.033 in]
Centerline, DIMM Sockets
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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 5**
Connector System: **Board-to-Component**
Number of Positions: **288**
Termination Method to PCB: **Surface Mount**
Module Orientation: **Vertical**

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 5
Connector System	Board-to-Component

Configuration Features

Number of Keys	1
Number of Bays	2
Number of Rows	2
Number of Positions	288
Module Orientation	Vertical

Electrical Characteristics

DRAM Voltage	1.1 V
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Body Features

Latch Color	Natural
Latch Material	High Temperature Nylon



PCB Retention Feature Material	Stainless Steel
Connector Profile	Standard
Ejector Material Color	Natural
Module Key Type	DRAM
Ejector Location	Both Ends
Ejector Material	High Temperature Thermoplastic
Ejector Type	Rotary

Contact Features

Contact Underplating Material	Tin
Socket Style	DIMM
Contact Mating Area Plating Material Thickness	.76 µm[30 µin]
PCB Contact Termination Area Plating Material Thickness	3 µm[120 µin]
Contact Mating Area Plating Material	Gold (Au)
Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin
Contact Current Rating (Max)	1.5 A

Termination Features

Insertion Style	Direct Insert
Termination Post & Tail Length	.89 mm[.035 in]
Termination Method to PCB	Surface Mount

Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention	With
Mount Angle	Vertical
PCB Mount Retention Type	Tab
Mating Alignment Type	1 Key
Mating Alignment	With
PCB Mount Alignment Type	None

Housing Features

Housing Color	Natural
Housing Material	High Temperature Nylon
Centerline (Pitch)	.85 mm[.033 in]



Dimensions

Profile Height from PCB	21.3 mm[.083 in]
Row-to-Row Spacing	3 mm[.118 in]

Usage Conditions

Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
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Operation/Application

Circuit Application	High Speed Data
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	640
Packaging Method	Box & Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides




on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

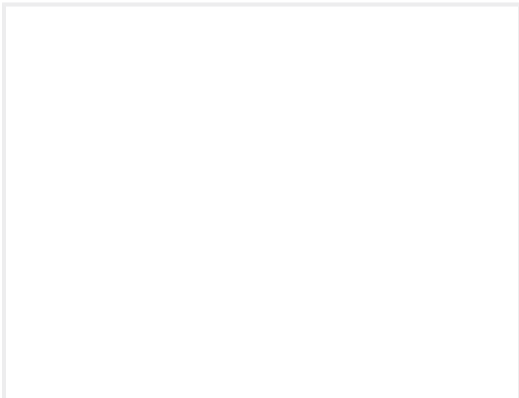


TE Part # 8-2355626-1
DDR5 DIMM BLACK HSG AND BLACK LATCH


Customers Also Bought



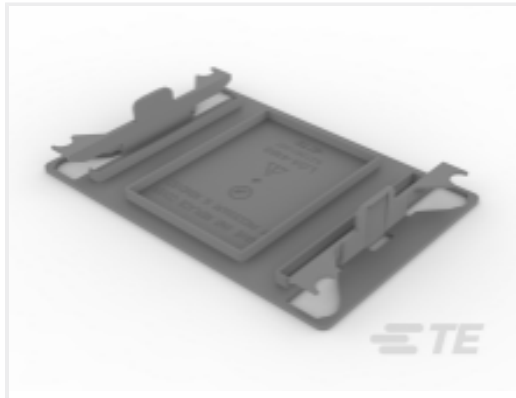
TE Part #1-2397198-1
SOCKET 4710 FOR ODM




TE Part #2454932-1
CA, MCIO 8X STR TO MCIO 8X STR



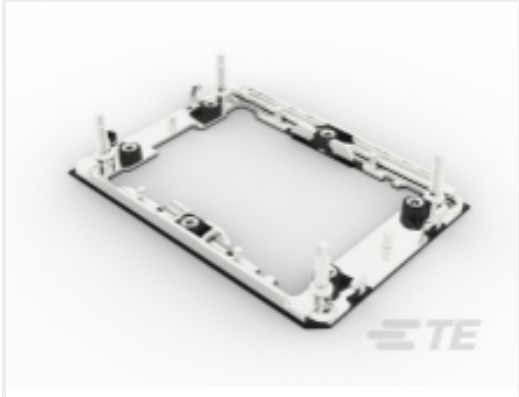
TE Part #2405569-1
LGA4710 BACKPLATE ASSY,SHORT STUD




TE Part #2-2330553-1
SOCKET P4/P5 DUST COVER, LGA4189




TE Part #2405568-1
LGA4710 TFLM ASSEMBLY W/O COVER




TE Part #2-2330550-1
SOCKET P4 BOLSTER PLATE ASSY, W /O COVER




TE Part #1-2351053-3
LGA4677/LGA4710 SOCKET COVER



TE Part #2-2355632-1
DDR5 NORMAL NATURAL HSG & NATURAL LATCH



TE Part #8-2450122-1
DDR5 DIMM 287P,black hsg&black latch



TE Part #8-2450125-1
DDR5 DIMM 287P,natural hsg&natural latch

Documents

Product Drawings
DDR5 DIMM NATURAL HSG AND NATURAL LATCH
English



CAD Files

Customer View Model

[ENG_CVM_CVM_8-2355632-1_A.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_8-2355632-1_A.3d_stp.zip](#)

English

Customer View Model

[ENG_CVM_CVM_8-2355632-1_A.3d_igs.zip](#)

English

3D PDF

3D

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Application Specification](#)

English